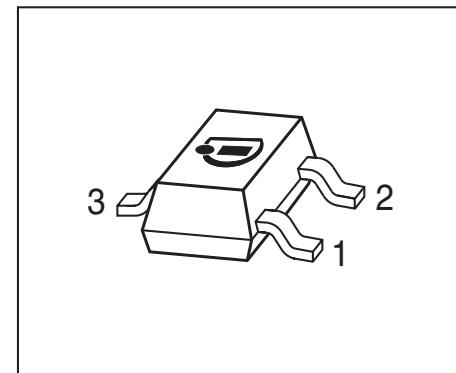


## NPN Silicon AF Transistors

- For general AF applications
- High current gain
- Low collector-emitter saturation voltage
- Complementary type: BCW68 (PNP)
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101



Type	Marking	Pin Configuration			Package
BCW66KF	EFs	1=B	2=E	3=C	SOT23
BCW66KG	EGs	1=B	2=E	3=C	SOT23
BCW66KH	EHs	1=B	2=E	3=C	SOT23

## Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	45	V
Collector-base voltage	$V_{CBO}$	75	
Emitter-base voltage	$V_{EBO}$	5	
Collector current	$I_C$	800	mA
Peak collector current, $t_p \leq 10 \text{ ms}$	$I_{CM}$	1	A
Base current	$I_B$	100	mA
Peak base current	$I_{BM}$	200	
Total power dissipation- $T_S \leq 115 \text{ }^\circ\text{C}$	$P_{tot}$	500	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-65 ... 150	

## Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{thJS}$	$\leq 70$	K/W

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage $I_C = 10 \text{ mA}, I_B = 0$	$V_{(\text{BR})\text{CEO}}$	45	-	-	V
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$	$V_{(\text{BR})\text{CBO}}$	75	-	-	
Emitter-base breakdown voltage $I_E = 10 \mu\text{A}, I_C = 0$	$V_{(\text{BR})\text{EBO}}$	5	-	-	
Collector-base cutoff current $V_{CB} = 45 \text{ V}, I_E = 0$ $V_{CB} = 45 \text{ V}, I_E = 0, T_A = 150^\circ\text{C}$	$I_{\text{CBO}}$	-	-	0.02 20	$\mu\text{A}$
Emitter-base cutoff current $V_{EB} = 5 \text{ V}, I_C = 0$	$I_{\text{EBO}}$	-	-	20	nA
DC current gain <sup>2)</sup> $I_C = 100 \mu\text{A} - 10 \text{ mA}, V_{CE} = 1 \text{ V}, \text{hFE-grp.F}$ $I_C = 100 \mu\text{A} - 10 \text{ mA}, V_{CE} = 1 \text{ V}, \text{hFE-grp.G}$ $I_C = 100 \mu\text{A} - 10 \text{ mA}, V_{CE} = 1 \text{ V}, \text{hFE-grp.H}$ $I_C = 100 \text{ mA}, V_{CE} = 1 \text{ V}, \text{hFE-grp.F}$ $I_C = 100 \text{ mA}, V_{CE} = 1 \text{ V}, \text{hFE-grp.G}$ $I_C = 100 \text{ mA}, V_{CE} = 1 \text{ V}, \text{hFE-grp.H}$ $I_C = 500 \text{ mA}, V_{CE} = 1 \text{ V}, \text{hFE-grp.F, G, H}$	$h_{\text{FE}}$	75 110 180 100 160 250 250 40	- - - 160 250 350 -	- - - 250 400 630 -	-
Collector-emitter saturation voltage <sup>2)</sup> $I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$ $I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$	$V_{\text{CEsat}}$	- -	- -	0.3 0.45	V
Base emitter saturation voltage <sup>2)</sup> $I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$ $I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$	$V_{\text{BEsat}}$	- -	- -	1.25 1.25	

<sup>1</sup>For calculation of  $R_{\text{thJA}}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

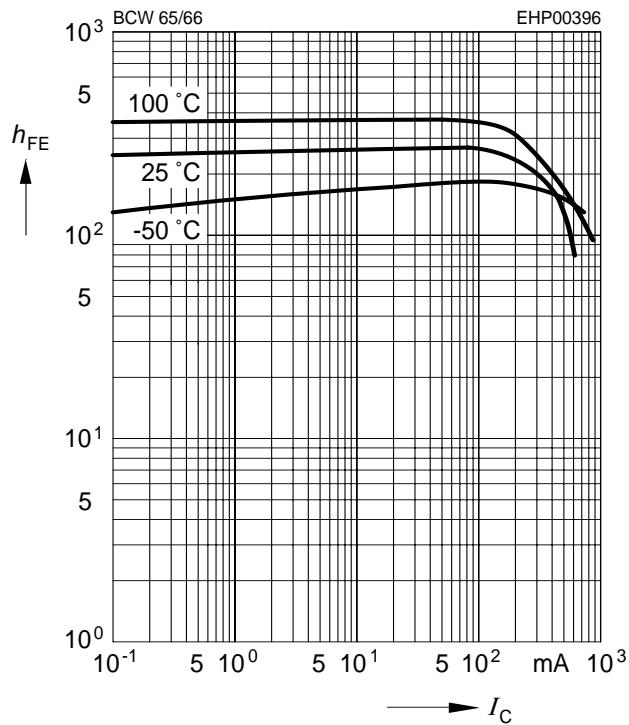
<sup>2</sup>Pulse test:  $t < 300\mu\text{s}; D < 2\%$

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>AC Characteristics</b>					
Transition frequency $I_C = 50 \text{ mA}, V_{CE} = 5 \text{ V}, f = 20 \text{ MHz}$	$f_T$	-	170	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	$C_{cb}$	-	3	-	pF
Emitter-base capacitance $V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}$	$C_{eb}$	-	40	-	

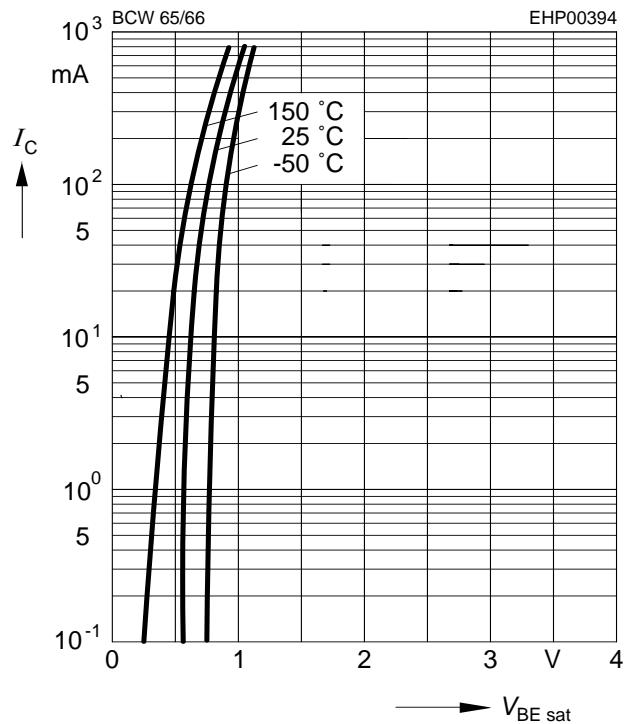
**DC current gain  $h_{FE} = f(I_C)$**

$V_{CE} = 1 \text{ V}$



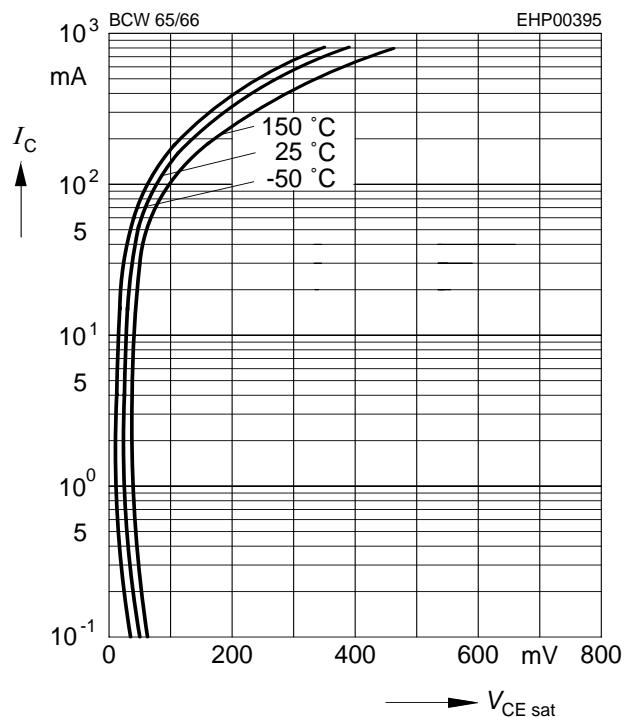
**Base-emitter saturation voltage**

$I_C = f(V_{BEsat})$ ,  $h_{FE} = 10$



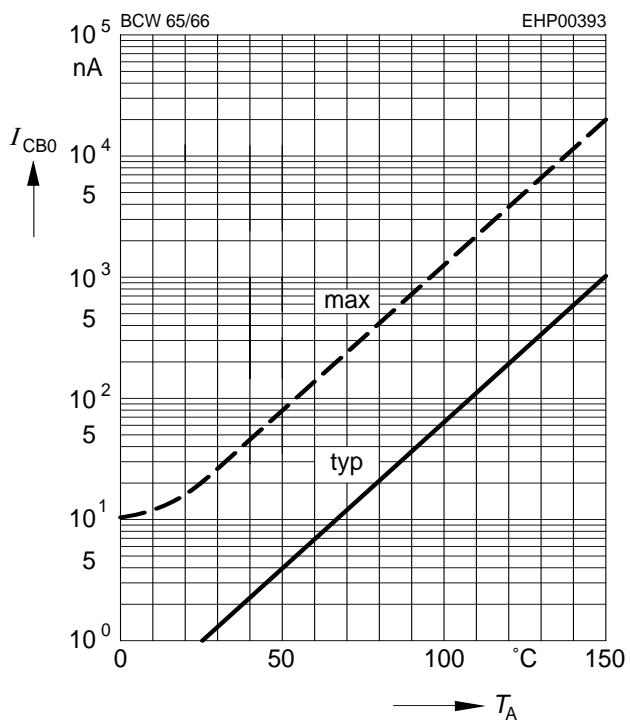
**Collector-emitter saturation voltage**

$I_C = f(V_{CEsat})$ ,  $h_{FE} = 10$

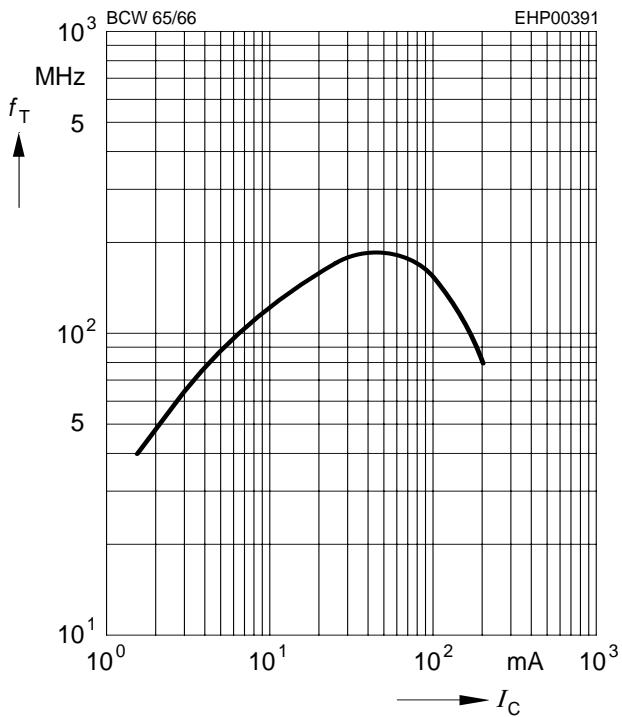


**Collector cutoff current  $I_{CBO} = f(T_A)$**

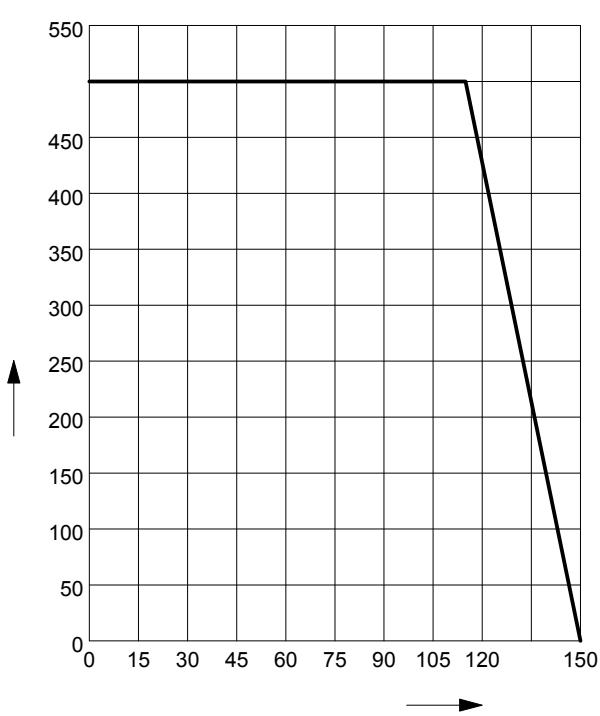
$V_{CB} = V_{CEmax}$



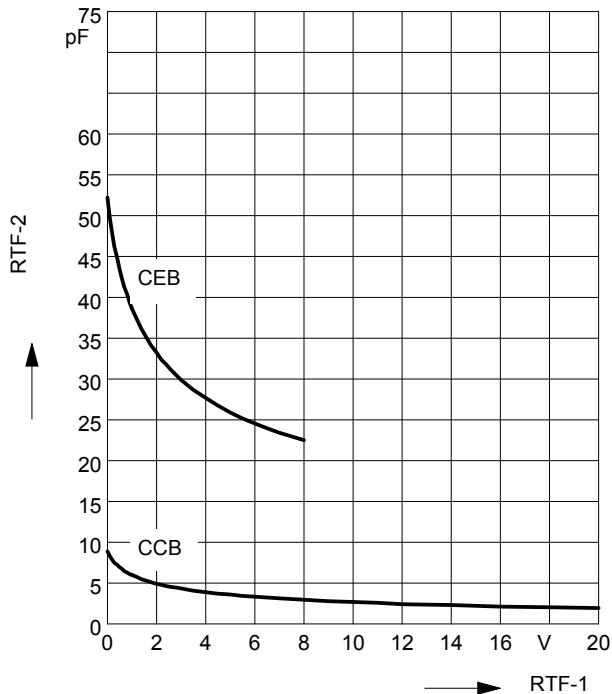
**Transition frequency**  $f_T = f(I_C)$   
 $V_{CE} = 5 \text{ V}$



**Total power dissipation**  $P_{\text{tot}} = f(T_S)$

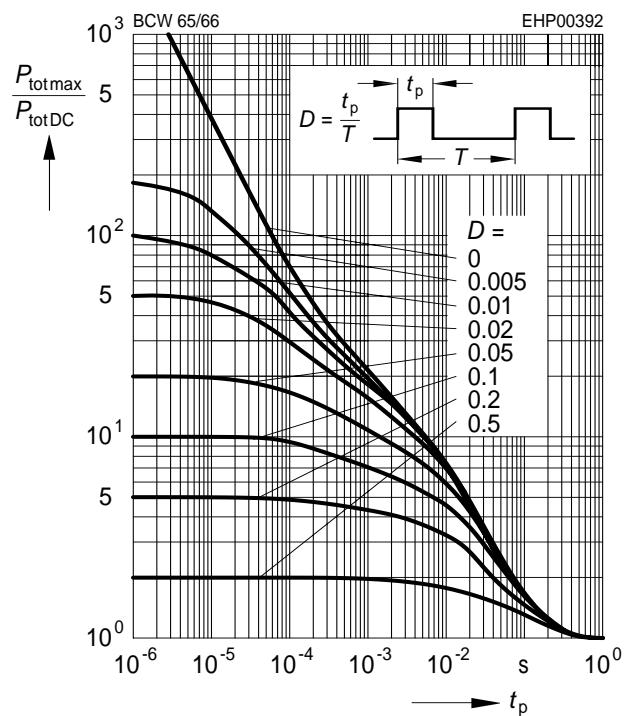


**Collector-base capacitance**  $C_{cb} = f(V_{CB})$   
**Emitter-base capacitance**  $C_{eb} = f(V_{EB})$

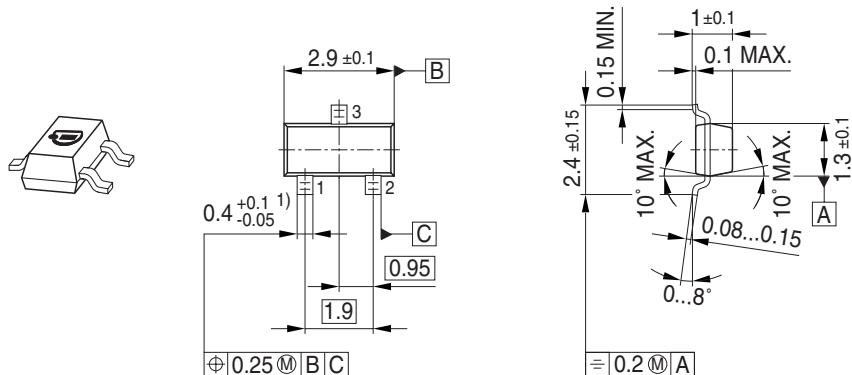


**Permissible Pulse Load**

$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

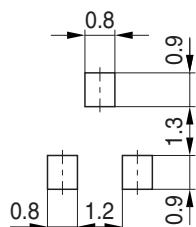


## Package Outline

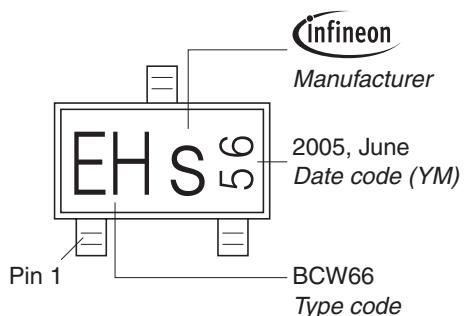


1) Lead width can be 0.6 max. in dambar area

## Foot Print

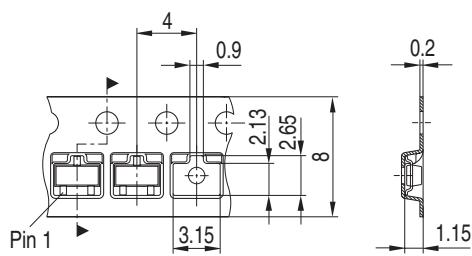


## Marking Layout (Example)



## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
Reel ø330 mm = 10.000 Pieces/Reel



**Edition 2009-11-16**

**Published by**  
**Infineon Technologies AG**  
**81726 Munich, Germany**

**© 2009 Infineon Technologies AG**  
**All Rights Reserved.**

### **Legal Disclaimer**

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

### **Information**

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office ([www.infineon.com](http://www.infineon.com)).

### **Warnings**

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

**Данный компонент на территории Российской Федерации****Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибуторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ Р В 0015-002 и ЭС РД 009

**Офис по работе с юридическими лицами:**

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru  
moschip.ru\_4

moschip.ru\_6  
moschip.ru\_9